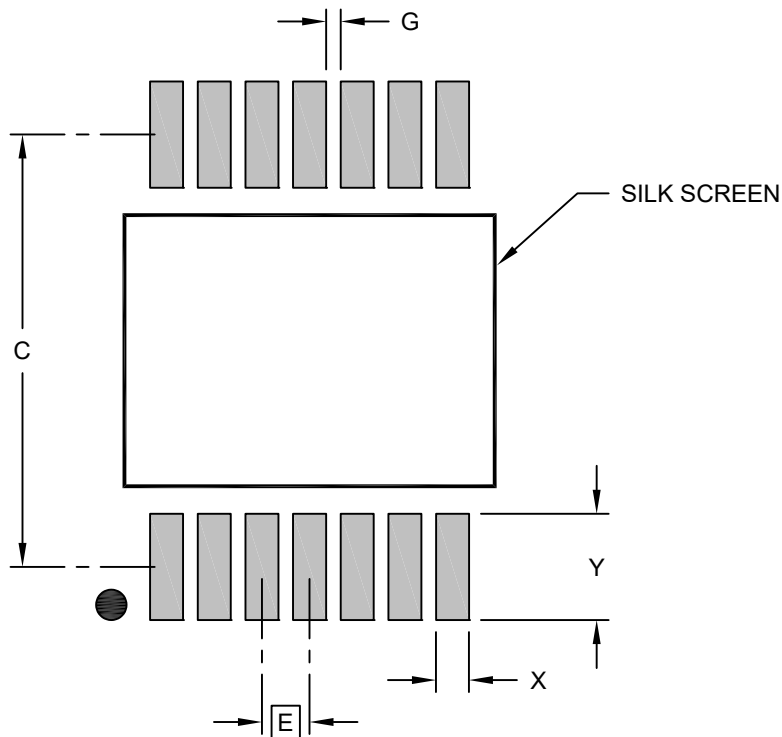


# 14-Lead Plastic Thin Shrink Small Outline Package [ST] – 4.4 mm Body [TSSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



## RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		5.90	
Contact Pad Width (X14)	X			0.45
Contact Pad Length (X14)	Y			1.45
Contact Pad to Contact Pad (X12)	G	0.20		

### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.